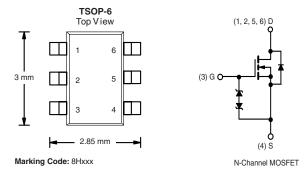


Vishay Siliconix

Automotive N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.045			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.066			
I _D (A)	4.0			
Configuration	Single			



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC
- AEC-Q101 Qualified^d
- Typical ESD Protection 800 V
- Find out more about Vishay's Automotive Grade Product Requirements at: www.vishay.com/applications



ROHS COMPLIANT HALOGEN FREE

ORDERING INFORMATION	
Package	TSOP-6
Lead (Pb)-free and Halogen-free	SQ3426EEV-T1-GE3

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 12		
Continuous Drain Current ^a	T _C = 25 °C	1	4.0		
	T _C = 125 °C	- I _D	2.5		
Continuous Source Current (Diode Conduction) ^a		I _S	0.9	А	
Pulsed Drain Current ^b		I _{DM}	24		
Single Pulse Avalanche Current	1 01 mll	I _{AS}	10		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	7	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P _D	1.1	W	
	T _A = 25 °C		0.7] vv	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient F	PCB Mount ^c	R_{thJA}	110	°C/W	
Junction-to-Foot (Drain)		R _{thJF}	40	C/VV	

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.

SQ3426EEV

Vishay Siliconix



SPECIFICATIONS T _C = 25 °C	, unless other	wise noted					
PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} = 0 V, I _D = - 250 μA		60	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V_{GS} , $I_D = -250 \mu A$	1.5	-	2.5	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current		V _{GS} = 0 V	V _{DS} = 60 V	-	-	- 1	μΑ
	I _{DSS}	V _{GS} = 0 V	V _{DS} = 60 V, T _J = 125 °C	-	-	- 50	
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	-	-	- 150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	24	-	-	Α
	В	V _{GS} = 10 V	I _D = 5 A	-	0.035	0.045	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V	I _D = 4 A	-	0.052	0.066	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 4 A		-	18	-	S
Dynamic ^b					•	•	
Input Capacitance	C _{iss}			-	360	-	
Output Capacitance	C _{oss}	V _{GS} = 0 V	$V_{GS} = 0 \text{ V}$ $V_{DS} = 30 \text{ V}, f = 1 \text{ MHz}$	-	60	-	pF
Reverse Transfer Capacitance	C _{rss}]		-	30	-	
Total Gate Charge ^c	Qg			-	8	-	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 4.5 V	$V_{DS} = 30 \text{ V}, I_{D} = 4 \text{ A}$	-	1.2	-	nC
Gate-Drain Charge ^c	Q _{gd}	1		-	1.0	-	
Turn-On Delay Time ^c	t _{d(on)}			-	5	-	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V, } R_L = 12 \Omega$ $I_D \cong 2.5 \text{ A, } V_{GEN} = 4.5 \text{ V, } R_g = 1 \Omega$		-	12	-	- ns
Turn-Off Delay Time ^c	t _{d(off)}			-	20	-	
Fall Time ^c	t _f			-	10	-	
Source-Drain Diode Ratings and Char-	acteristics T _C = 2	25 °C ^b					
Pulsed Current ^a	I _{SM}			-	-	24	Α
Forward Voltage	V_{SD}	I _F = 1.6 A, V _{GS} = 0 V		-	0.8	1.2	V

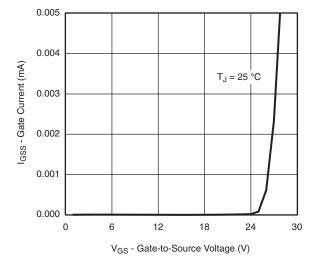
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

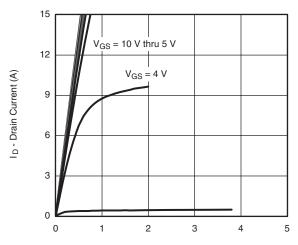
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



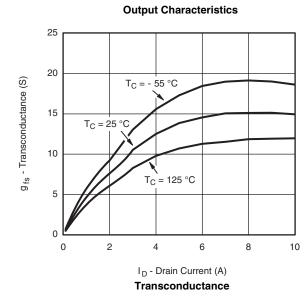
TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

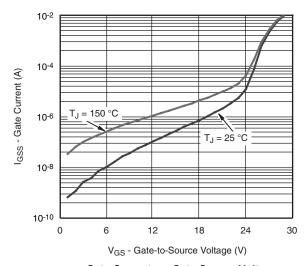


Gate Current vs. Gate-Source Voltage

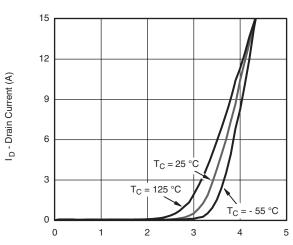


V_{DS} - Drain-to-Source Voltage (V)

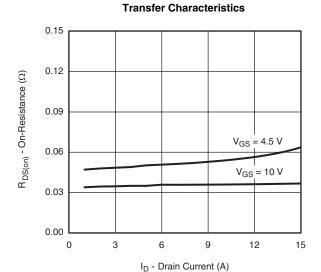




Gate Current vs. Gate-Source Voltage



V_{GS} - Gate-to-Source Voltage (V)

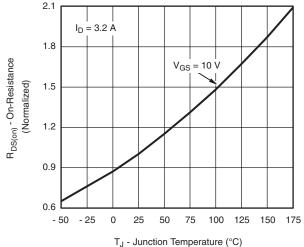


On-Resistance vs. Drain Current

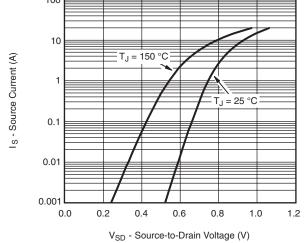
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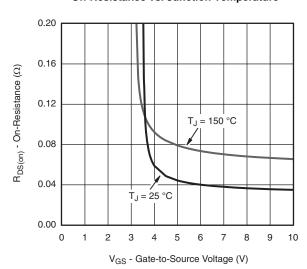
TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



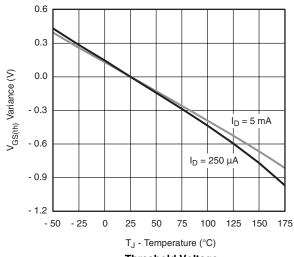
On-Resistance vs. Junction Temperature



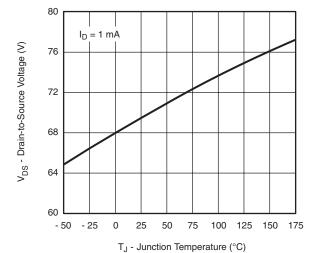
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-Source Voltage



Threshold Voltage

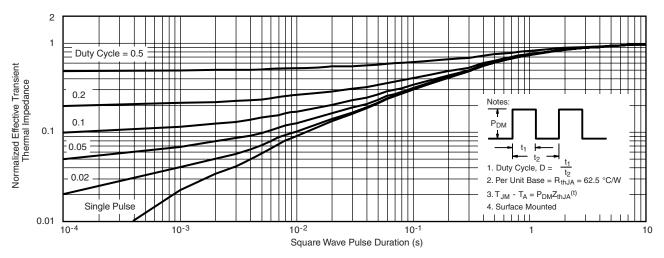


Drain-Source Breakdown vs. Junction Temperature





THERMAL RATINGS T_A = 25 °C, unless otherwise noted



Normalized thermal Transient Impedance, Junction-to-Case

Note

The characteristics shown in the graph. Normalized Transient Thermal Impedance Junction to Case (25 °C) is given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg265351.





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